



6p 2809 #2

219.40446X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Vassoudevane LEBONHEUR ET AL.

Serial No.: 09/964,709

Filing Date: September 28, 2001

For: METHOD OF IMPROVING THERMAL PERFORMANCE IN
FLIP CHIP/INTEGRAL HEAT SPREADER PACKAGES USING
LOW MODULUS THERMAL INTERFACE MATERIAL

LETTER SUBMITTING FORMAL DRAWINGS

Assistant Commissioner for Patents
Washington, D.C. 20231

November 6, 2001

RECEIVED
NOV 13 2001
TC 2000 MAIL ROOM

Sir:

Submitted herewith are four (4) sheets of formal drawings illustrating Figs.

1-5 in connection with the above-identified application.

Respectfully submitted,

ANTONELLI, TERRY, STOUT & KRAUS, LLP

Ronald J. Shore
Registration No. 28,577

RJS:alw
(703) 312-6600

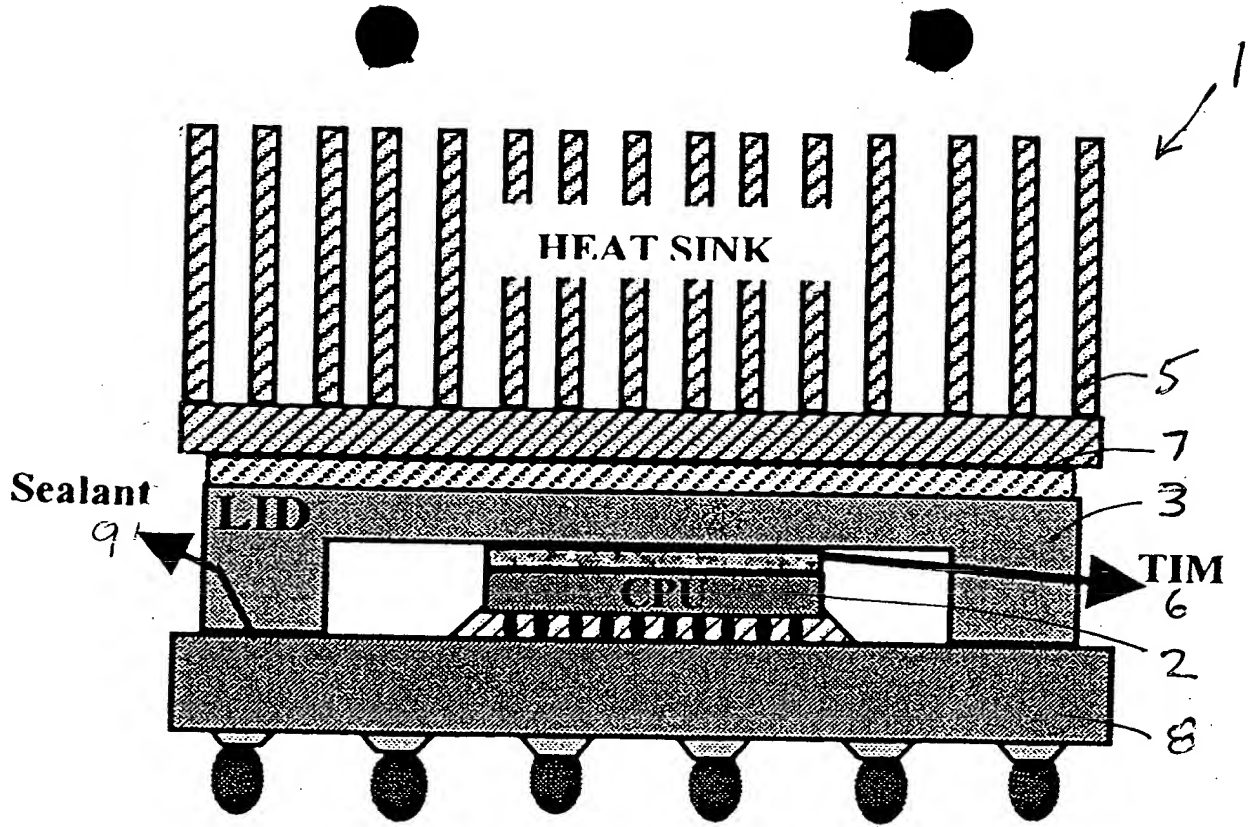


FIG. 1

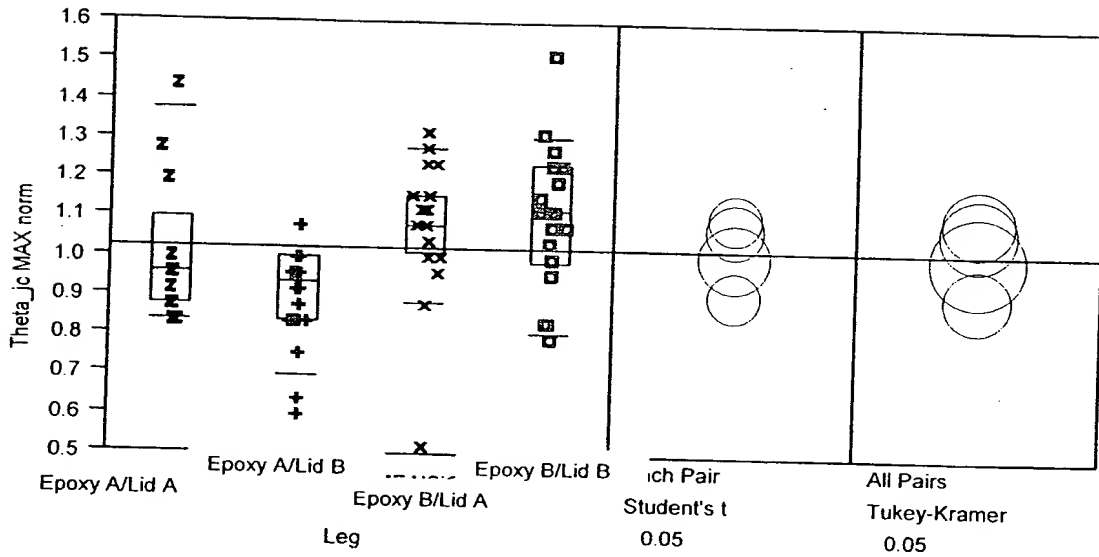


FIG. 2

T08260" 60449660

FIG. 3

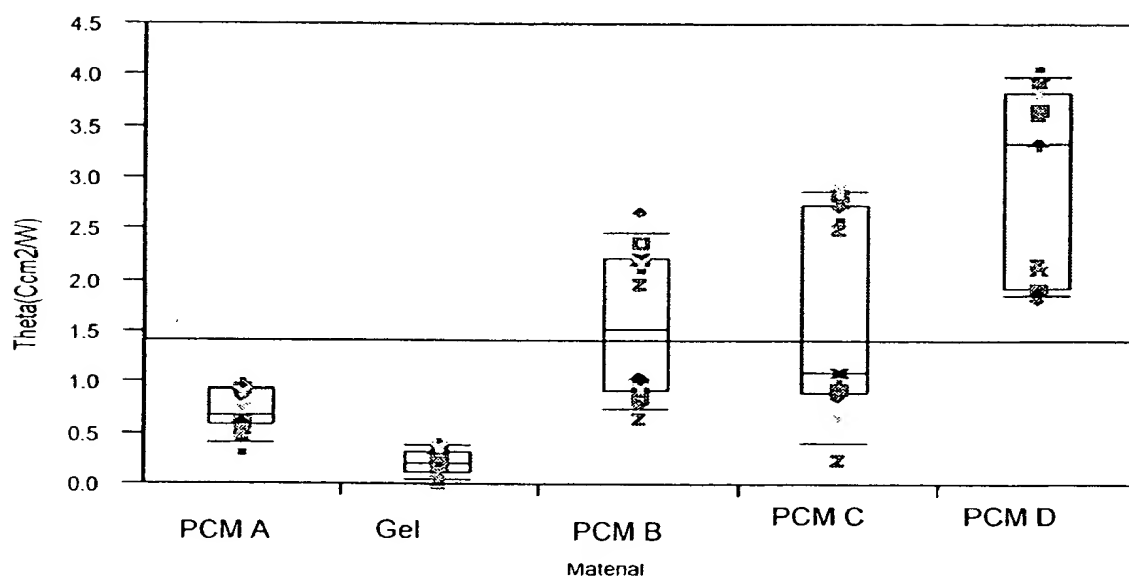
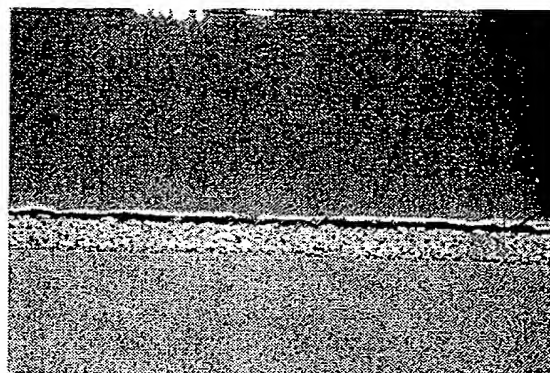


FIG. 4

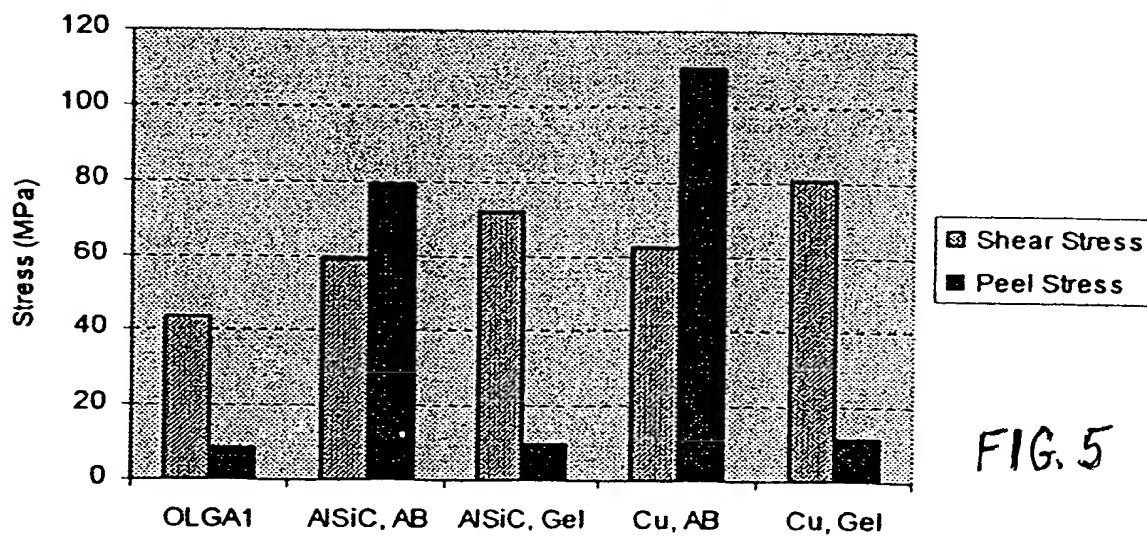


FIG. 5

T08260" 60449660

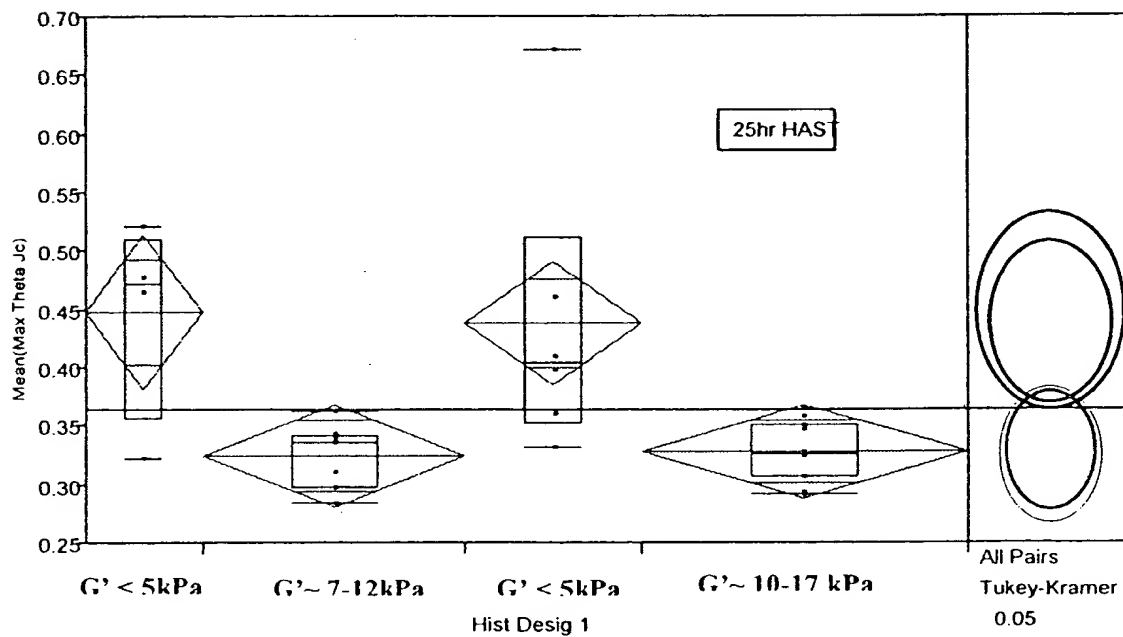
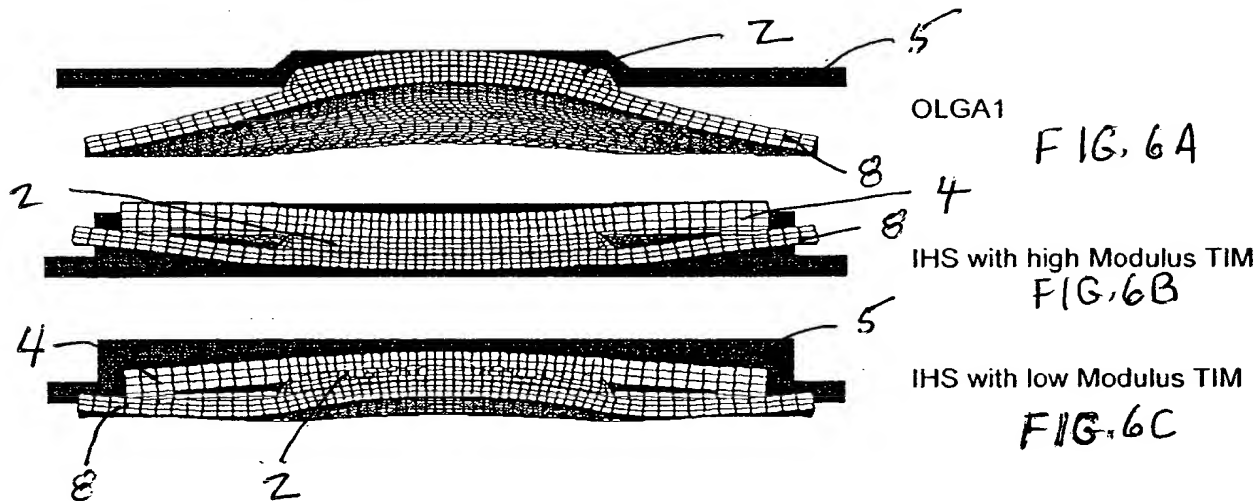


FIG. 7